

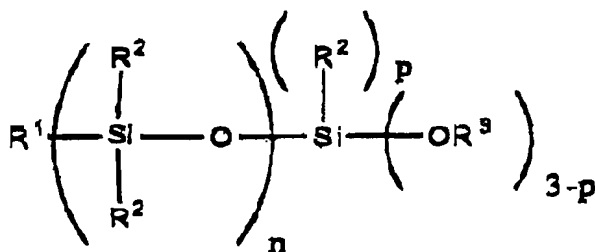
AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A one-component liquid crystal sealing composition ~~characterized by being an epoxy resin composition of one-component type~~ comprising (1) an alkoxysilyl group-containing modified epoxy resin obtained by de-alcohol condensation reaction of (a) an epoxy resin having at least one hydroxyl group in one molecule and (b) an alkoxysilyl group-containing compound represented by formula (2):

[Formula 2]



wherein R^1 represents a C1 to C8 alkyl group, a phenyl group or a C1 to C8 alkenyl group, each of which may have a C1 to C8 alkoxy group, vinyl group, acryloyl group, methacryloyl group, carboxyl group, epoxy group, glycidyl group, amino group and mercapto group, R^2 represents a C1 to C8 alkoxysilyl group, a C1 to C8 alkyl group or a phenyl group, R^3 represents a C1 to C8 alkyl group, n is an integer of 0 to 6, and p is an integer of 0 to 2, (2) a heat latent epoxy curing agent and (3) a filler having an average particle diameter of 0.1 to 10 μm .

2. (Currently Amended) The one-component liquid crystal sealing composition according to claim 1, further ~~comprises~~ comprising (4) epoxy resin having at least 1.2 epoxy groups on average in one molecule.

3. (Currently Amended) The one-component liquid crystal sealing composition according to claim ~~[[1 or]]~~ 2, wherein the alkoxysilyl group-containing modified epoxy resin (1) is contained in an amount of 1 to 30% by weight based on 100% by weight of the liquid crystal sealing composition.

4. (Currently Amended) The one-component liquid crystal sealing composition according to ~~any one of claims 1 to 3~~ claim 2, wherein at least one kind of the heat latent epoxy curing agent (2) is an amine-based heat latent curing agent, and its melting point or its softening temperature as determined by a ring and ball method is 100°C or more.

5. (Currently Amended) The one-component liquid crystal sealing composition according to ~~any one of claims 1 to 4~~ claim 2, wherein at least one kind of the heat latent epoxy curing agent (2) ~~described in claim 4~~ is an imidazole-based curing agent having a melting point of 130°C or more.

6. (Currently Amended) The one-component liquid crystal sealing composition according to ~~any one of claims 1 to 5~~ claim 2, wherein the filler (3) is contained in an amount of 5 to 30% by weight based on 100% by weight of the liquid sealing composition.

7. (Currently Amended) The one-component liquid crystal sealing composition according to ~~any one of claims 1 to 6~~ claim 2, wherein (5) an aprotic solvent compatible with epoxy resin and inert to an epoxy group and having a boiling point in the range of 140 to 220°C is contained in an amount of 5 to 30% by weight based on 100% by weight of the liquid crystal sealing composition.

8. (Currently Amended) A method of producing a liquid crystal display panel, which comprises applying the one-component liquid crystal sealing composition of claim 2 on a sealing site of a liquid crystal display panel and heat curing the composition ~~the heat-cured liquid crystal sealing composition according to any one of claims 1 to 7.~~

9. (Original) A liquid crystal display panel produced by the method of producing a liquid crystal display panel according to claim 8.

10. (New) The one-component liquid crystal sealing composition according to claim 1, wherein the alkoxysilyl group-containing modified epoxy resin (1) is contained in an amount of 1 to 30% by weight based on 100% by weight of the liquid crystal sealing composition.

11. (New) The one-component liquid crystal sealing composition according to claim 1, wherein at least one kind of the heat latent epoxy curing agent (2) is an amine-based heat latent curing agent, and its melting point or its softening temperature as determined by a ring and ball method is 100°C or more.

12. (New) The one-component liquid crystal sealing composition according to claim 1, wherein at least one kind of the heat latent epoxy curing agent (2) is an imidazole-based curing agent having a melting point of 130°C or more.

13. (New) The one-component liquid crystal sealing composition according to claim 1, wherein the filler (3) is contained in an amount of 5 to 30% by weight based on 100% by weight of the liquid sealing composition.

14. (New) The one-component liquid crystal sealing composition according to claim 1, wherein (5) an aprotic solvent compatible with epoxy resin and inert to an epoxy group and having a boiling point in the range of 140 to 220°C is contained in an amount of 5 to 30% by weight based on 100% by weight of the liquid crystal sealing composition.

15. (New) A method of producing a liquid crystal display panel, which comprises applying the one-component liquid crystal sealing composition of claim 1 on a sealing site of a liquid crystal display panel and heat curing the composition.

16. (New) A liquid crystal display panel produced by the method of producing a liquid crystal display panel according to claim 15.